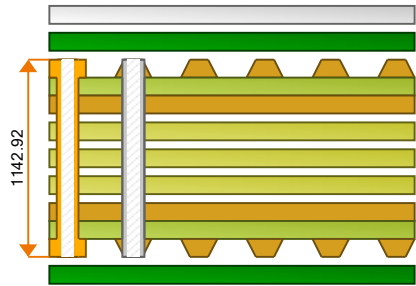




Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	ϵ_r	Loss Tangent	Impedance ID
		Screened Ident							
		LPI Mask			25.400		4.000	0.0200	
1		RF Core	Signal	35.000	35.000				
2		RF Core	Plane	250.000	250.000	0.000	3.480	0.0031	
		PrePreg 7628		35.000	35.000				
		PrePreg 7628		200.660	200.660	45.000	4.200	0.0195	
		PrePreg 3113		101.600	101.600	53.000	4.200	0.0195	
		PrePreg 7628		200.660	200.660	45.000	4.200	0.0195	
3		RF Core	Plane	35.000	35.000				
4		RF Core	Signal	250.000	250.000	0.000	3.480	0.0031	
		LPI Mask			35.000				
		LPI Mask			25.400		4.000	0.0195	



Copper Thickness = 140.000 | Dielectric Thickness = 1002.920 | Solder Mask Thickness = 50.800 | Stack Up Thickness = 1142.920 | Stack Up Thickness with Soldermask = 1193.720
Stack Up Cost = 17.60

Drill Image	1st Layer	2nd Layer	Column Position	Drill Type
	1	4	2	Mechanical NPTH
	1	4	1	Mechanical PTH

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Polar Samples	ID/001	Screened Ident	Ident	600-001	1	0.10	0.10	1	0.10
Polar Samples	SM/005	LPI Mask			2	0.50	1.00	2	1.00
Rogers		RF Core	Hydrocarbon / ceramic		2	10.00	20.00	2	20.00
Polar Samples	PP/005	PrePreg 7628	Dielectric	300-005	2	1.00	2.00	2	2.00
Polar Samples	PP/003	PrePreg 3113	Dielectric	300-003	1	1.00	1.00	1	1.00
							24.10	24.10	

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 24.10 |

Notes

StackName: Master	Version:	Revision:	Modification:	Date of Revision:	Editor
Date: 06/03/2019	Associated Documents:				
Author:					
Department:					
Site:					

